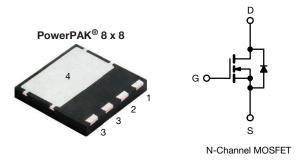
**Vishay Siliconix** 



## **E Series Power MOSFET**



PRODUCT SUMMARY						
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650					
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V 0.208					
Q <sub>g</sub> max. (nC)	23					
Q <sub>gs</sub> (nC)	4					
Q <sub>gd</sub> (nC)	6					
Configuration	Single					

#### FEATURES

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (C<sub>o(er)</sub>)
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and halogen-free	SiHH240N60E-T1-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_c = 25 \degree C$ , unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	600	v	
Gate-source voltage			V <sub>GS</sub>	± 30	v	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	12		
	VGS AL TO V	T <sub>C</sub> = 100 °C		7	A	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	30		
Linear derating factor				0.63	W/°C	
Single pulse avalanche energy <sup>b</sup>			E <sub>AS</sub>	81	mJ	
Maximum power dissipation			PD	89	W	
Operating junction and storage temperature ra	ange		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 \text{ °C}$			alı . / alt	100	V/ns	
Reverse diode dv/dt c			dv/dt	28	V/IIS	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

- b.  $V_{DD}$  = 120 V, starting T<sub>J</sub> = 25 °C, L = 28.2 mH, R<sub>g</sub> = 25  $\Omega$ , I<sub>AS</sub> = 2.4 A
- c.  $I_{SD} \leq I_D, \, di/dt$  = 100 A/µs, starting  $T_J$  = 25  $^\circ C$





Maximum junction-to-ambient         R <sub>thJA</sub> 42         55         °C/W           Maximum junction-to-case (drain)         R <sub>thJC</sub> 1.0         1.4         °C/W           SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)         TEST CONDITIONS         MIN.         TYP.         MAX.         UNIT           Static         V <sub>DS</sub> V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA         600         -         -         V	PARAMETER	SYMBOL	TYP.	MAX			UNIT		
$ \begin{array}{ c c c c c c } \hline \begin{tabular}{ c c c c c } \hline \begin{tabular}{ c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$									
$\begin{array}{ c c c c c } \hline \textbf{SPECIFICATIONS}(T_{J} = 25 \ ^{\circ}\text{C}, unless otherwise noted}) \\ \hline \textbf{PARAMETER} & \textbf{SYMBOL} & \textbf{TEST CONDITIONS} & \textbf{MIN}. & \textbf{TYP}, & \textbf{MAX}. & \textbf{UNIT} \\ \hline \textbf{Static} \\ \hline \textbf{Drain-source breakdown voltage} & V_{DS} & V_{GS} = 0 \ V, \ I_{D} = 250 \ \mu\text{A} & - & 0.63 & - & V''C \\ \hline \textbf{Gate-source threshold voltage (N)} & V_{GS}(m) & V_{DS} = V_{GS}, \ I_{D} = 1 \ \text{mA} & - & 0.63 & - & V''C \\ \hline \textbf{Gate-source threshold voltage (N)} & V_{GS}(m) & V_{DS} = V_{GS}, \ I_{D} = 250 \ \mu\text{A} & 3.0 & - & 5.0 & V \\ \hline \textbf{Gate-source threshold voltage (N)} & V_{GS}(m) & V_{DS} = V_{GS}, \ I_{D} = 250 \ \mu\text{A} & 3.0 & - & 5.0 & V \\ \hline \textbf{Gate-source threshold voltage (N)} & V_{GS}(m) & V_{DS} = 420 \ V & - & - & \pm 100 \ \text{mA} \\ \hline \textbf{Gate-source leakage} & I_{GSS} & V_{GS} = \pm 20 \ V & - & - & \pm 100 \ \text{mA} \\ \hline \textbf{Zero gate voltage drain current} & I_{DSS} & V_{DS} = 600 \ V, \ V_{GS} = 0 \ V, \ U_{DS} = 20 \ V, \ I_{D} = 5.5 \ A & - & 4 & - & S \\ \hline \textbf{Drain-source on-state resistance} & \textbf{R}_{DS(m)} & V_{DS} = 100 \ V, \ I_{D} = 5.5 \ A & - & 4 & - & S \\ \hline \textbf{Drain-source on-state resistance} & C_{Iss} & V_{DS} = 20 \ V, \ I_{D} = 5.5 \ A & - & 4 & - & S \\ \hline \textbf{Dynamic} & & & & & & & & & & & & & & & & & & &$	,						°C/W		
$\begin{array}{ c c c c c c } \hline PARAMETER & SYMBOL & TEST CONDITIONS & MIN. & TYP. & MAX. & UNIT \\ \hline Static \\ \hline Drain-source breakdown voltage & V_{DS} & V_{GS} = 0 V, I_D = 250 \ \mu A & 600 & - & - & V \\ \hline O_S temperature coefficient & \Delta V_{DS}/T_J & Reference to 25 °C, I_D = 1 \ mA & - & 0.63 & - & V'^{\circ}C \\ \hline Gate-source threshold voltage (N) & V_{GS(th)} & V_{DS} = V_{GS}, I_D = 250 \ \mu A & 3.0 & - & 5.0 & V \\ \hline Gate-source threshold voltage (N) & V_{GS(th)} & V_{DS} = V_{GS}, I_D = 250 \ \mu A & 3.0 & - & 5.0 & V \\ \hline Gate-source leakage & I_{GSS} & V_{GS} = 20 \ V & - & - & \pm 100 & nA \\ \hline V_{GS} = \pm 30 \ V & - & - & \pm 100 & nA \\ \hline V_{GS} = \pm 30 \ V & - & - & \pm 100 & nA \\ \hline V_{DS} = 00 \ V, V_{GS} = 0 \ V, V_{GS} = 0 \ V & - & - & 10 \\ \hline Drain-source on-state resistance & R_{DS(on)} & V_{GS} = 10 \ V & I_D = 5.5 \ A & - & 0.208 & 0.240 \ \Omega \\ \hline Drain-source on-state resistance & R_{DS(on)} & V_{GS} = 10 \ V \\ \hline Dy_{DS} = 480 \ V, V_{GS} = 0 \ V, I_D = 5.5 \ A & - & 4 \ - & S \\ \hline Dynamic & & & & & & & & & & & & & & & & & & &$		i itnjC	1.0	1.4		<u> </u>			
$\begin{tabular}{ c c c c c } \hline Static & & & & & & & & & & & & & & & & & & &$	<b>SPECIFICATIONS</b> ( $T_J = 25 \ ^{\circ}C$ ,	unless otherwi	se noted)						
$\begin{array}{ c c c c c } \hline \mbox{Drain-source breakdown voltage} & V_{DS} & V_{DS} & V_{DS} = 0 \ V, \ I_D = 250 \ \mu A & 600 & - & - & V \\ \hline V_{DS} \ temperature \ coefficient & \Delta V_{DS}/T_J & Reference \ to 25 \ ^{\circ}C, \ I_D = 1 \ mA & - & 0.63 & - & V/^{\circ}C \\ \hline \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Static	•			•			•	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	600	-	-	V	
$ \begin{array}{c c c c c c c } Gate-source leakage & I_{GSS} & V_{GS} = \pm 20 & - & - & \pm 100 & nA \\ \hline V_{GS} = \pm 30 & - & - & \pm 1 & \muA \\ \hline V_{DS} = 600 & V, V_{GS} = 0 & - & - & 10 \\ \hline V_{DS} = 480 & V, V_{GS} = 0 & - & - & 10 \\ \hline V_{DS} = 480 & V, V_{GS} = 0 & V, T_{J} = 125 & - & - & 10 \\ \hline Prime rational conductance & R_{DS(on)} & V_{GS} = 10 & V & I_{D} = 5.5 & - & - & 10 \\ \hline Prime rational conductance & R_{DS(on)} & V_{GS} = 10 & V & I_{D} = 5.5 & - & - & 4 & - & S \\ \hline Prime rational conductance & R_{DS(on)} & V_{GS} = 0 & V, I_{J} = 5.5 & - & 4 & - & S \\ \hline Prime rational conductance & C_{ISS} & V_{DS} = 20 & V, I_{D} = 5.5 & - & 4 & - & S \\ \hline Prime rational conductance & C_{ISS} & V_{DS} = 100 & V, I_{D} = 5.5 & - & - & - & - & - & - & - & - & S \\ \hline Output capacitance & C_{ISS} & V_{DS} = 100 & V, I_{D} = 5.5 & - & - & - & - & - & - & - & S \\ \hline Prime related & C_{ISS} & V_{DS} = 0 & V, I_{D} = 5.5 & - & - & - & - & - & - & - & - & S \\ \hline Prime related & C_{ISS} & V_{DS} = 0 & V, I_{D} = 0 & V_{DS} = 0 & V_{DS} = 0 & - & - & - & - & - & - & - & - & - &$	V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.63	-	V/°C	
$ \begin{array}{c c c c c c c } Gate-source leakage & I_{GSS} & V_{GS} = \pm 20 & - & - & \pm 100 & nA \\ \hline V_{GS} = \pm 30 & - & - & \pm 1 & \muA \\ \hline V_{DS} = 600 & V, V_{GS} = 0 & - & - & 10 \\ \hline V_{DS} = 480 & V, V_{GS} = 0 & - & - & 10 \\ \hline V_{DS} = 480 & V, V_{GS} = 0 & V, T_{J} = 125 & - & - & 10 \\ \hline Prime rational conductance & R_{DS(on)} & V_{GS} = 10 & V & I_{D} = 5.5 & - & - & 10 \\ \hline Prime rational conductance & R_{DS(on)} & V_{GS} = 10 & V & I_{D} = 5.5 & - & - & 4 & - & S \\ \hline Prime rational conductance & R_{DS(on)} & V_{GS} = 0 & V, I_{J} = 5.5 & - & 4 & - & S \\ \hline Prime rational conductance & C_{ISS} & V_{DS} = 20 & V, I_{D} = 5.5 & - & 4 & - & S \\ \hline Prime rational conductance & C_{ISS} & V_{DS} = 100 & V, I_{D} = 5.5 & - & - & - & - & - & - & - & - & S \\ \hline Output capacitance & C_{ISS} & V_{DS} = 100 & V, I_{D} = 5.5 & - & - & - & - & - & - & - & S \\ \hline Prime related & C_{ISS} & V_{DS} = 0 & V, I_{D} = 5.5 & - & - & - & - & - & - & - & - & S \\ \hline Prime related & C_{ISS} & V_{DS} = 0 & V, I_{D} = 0 & V_{DS} = 0 & V_{DS} = 0 & - & - & - & - & - & - & - & - & - &$	Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μΑ	3.0	-	5.0	V	
$ \begin{array}{ c c c c c } \hline V_{GS} = \pm 30 \ V & - & - & \pm 1 & \mu A \\ \hline V_{GS} = \pm 30 \ V & - & - & \pm 1 & \mu A \\ \hline V_{DS} = 600 \ V, \ V_{GS} = 0 \ V & - & - & 1 & \mu A \\ \hline V_{DS} = 480 \ V, \ V_{GS} = 0 \ V, \ T_{J} = 125 \ ^{\circ}C & - & - & 10 & \mu A \\ \hline Drain-source on-state resistance & R_{DS(on)} & V_{GS} = 10 \ V & I_{D} = 5.5 \ A & - & 0.208 & 0.240 & \Omega \\ \hline Forward transconductance \ ^{a} & g_{fs} & V_{DS} = 20 \ V, \ I_{D} = 5.5 \ A & - & 4 & - & S \\ \hline Dynamic & & & & & & & & & & & & & & & & & & &$				V <sub>GS</sub> = ± 20 V	-	-	± 100	nA	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gale-source leakage	IGSS		V <sub>GS</sub> = ± 30 V	-	-	± 1	μA	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	7		V <sub>DS</sub> =	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	1	μA	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Zero gate voltage drain current	IDSS	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	-	10		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Drain-source on-state resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	V <sub>GS</sub> = 10 V I <sub>D</sub> = 5.5 A		0.208	0.240	Ω	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Forward transconductance <sup>a</sup>		V <sub>DS</sub> = 20 V, I <sub>D</sub> = 5.5 A		-	4	-	S	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Dynamic		•		•		•		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Input capacitance	C <sub>iss</sub>		$V_{cc} = 0.V$		783	-	-	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Output capacitance		$V_{DS} = 100 V,$		-	50	-		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Reverse transfer capacitance					5	-		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		C <sub>o(er)</sub>				32	-	pF	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		C <sub>o(tr)</sub>	v <sub>DS</sub> = 0 v to 480 v, v <sub>GS</sub> = 0 v		-	187	-		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Total gate charge	Qg			-	15	23		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 5.5 \text{ A}, V_{DS} = 480 \text{ V}$	-	4	-	nC	
Rise time $t_r$ $V_{DD} = 480 \text{ V}, \text{ I}_D = 5.5 \text{ A},$ -         14         28           Turn-off delay time $t_{d(off)}$ $V_{GS} = 10 \text{ V}, \text{ R}_g = 9.1 \Omega$ -         26         52	Gate-drain charge	Q <sub>gd</sub>			-	6	-		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Turn-on delay time	÷			-	15	30		
Turn-off delay time $t_{d(off)}$ $V_{GS} = 10 \text{ V}, \text{ R}_g = 9.1 \Omega$ -2652	Rise time				-	14	28	ns	
	Turn-off delay time	t <sub>d(off)</sub>			-	26	52		
	Fall time		1		-	14	28	1	

f = 1 MHz, open drain

 $T_J$  = 25 °C,  $I_S$  = 5.5 A,  $V_{GS}$  = 0 V

 $T_J=25\ ^\circ C,\ I_F=I_S=5.5\ A,$ 

 $di/dt = 100 \text{ A}/\mu \text{s}, \text{ V}_{\text{R}} = 25 \text{ V}$ 

MOSFET symbol

p - n junction diode

showing the integral reverse

0.8

\_

-

-

-

-

1.5

-

-209

2.1

18

3.0

12

30

1.2

418

4.2

\_

Ω

А

٧

ns

μC

А

#### Notes

Gate input resistance

Diode forward voltage

Reverse recovery time

Reverse recovery charge

Reverse recovery current

**Drain-Source Body Diode Characteristics** 

Continuous source-drain diode current

Pulsed diode forward current

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ 

 $R_{g}$ 

Is

I<sub>SM</sub>

V<sub>SD</sub>

t<sub>rr</sub>

Q<sub>rr</sub>

I<sub>RRM</sub>

b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ 



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#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

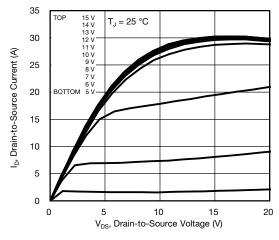
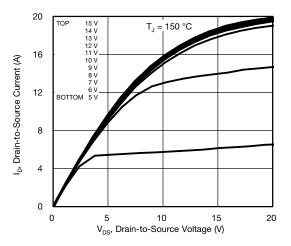
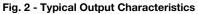


Fig. 1 - Typical Output Characteristics





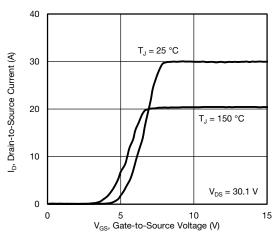


Fig. 3 - Typical Transfer Characteristics

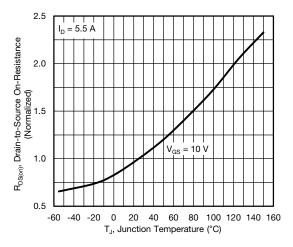


Fig. 4 - Normalized On-Resistance vs. Temperature

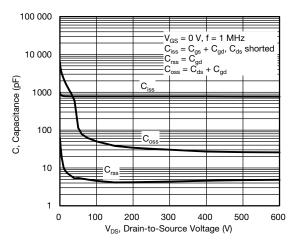


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

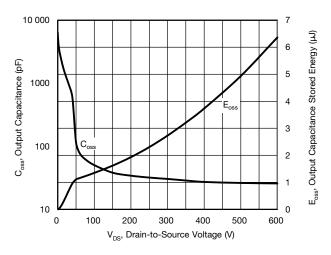


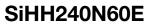
Fig. 6 - Coss and Eoss vs. VDS

3

Document Number: 92334

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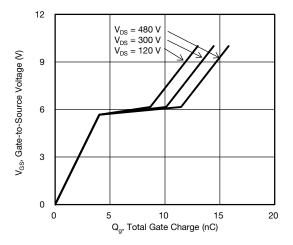


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

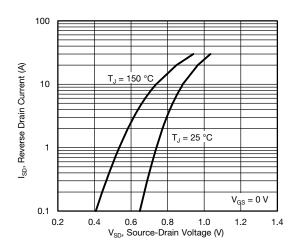


Fig. 8 - Typical Source-Drain Diode Forward Voltage

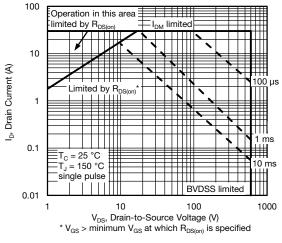


Fig. 9 - Maximum Safe Operating Area

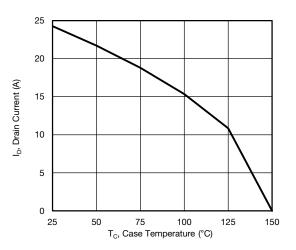


Fig. 10 - Maximum Drain Current vs. Case Temperature

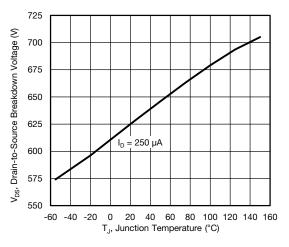


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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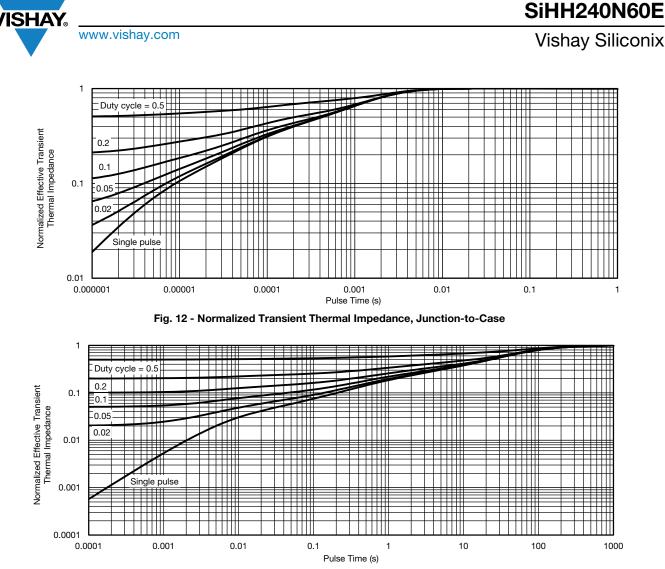


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

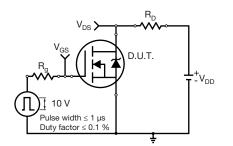


Fig. 14 - Switching Time Test Circuit

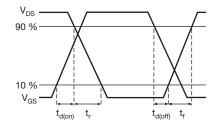


Fig. 15 - Switching Time Waveforms



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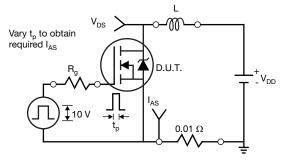


Fig. 16 - Unclamped Inductive Test Circuit

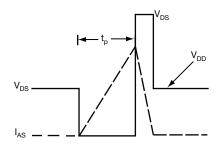


Fig. 17 - Unclamped Inductive Waveforms

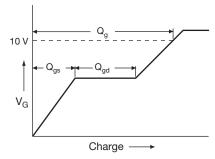


Fig. 18 - Basic Gate Charge Waveform

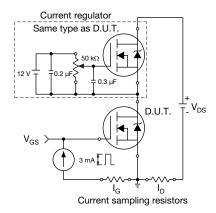
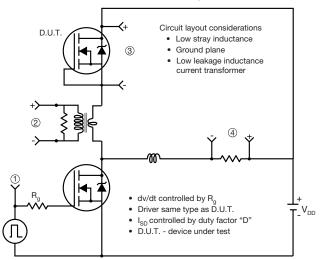


Fig. 19 - Gate Charge Test Circuit

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#### Peak Diode Recovery dv/dt Test Circuit



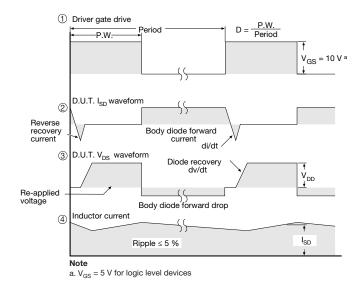
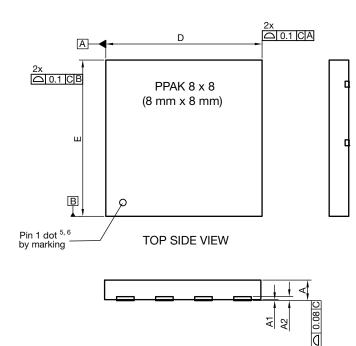


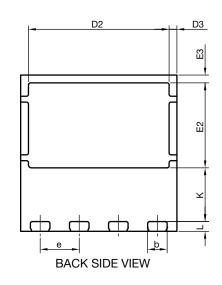
Fig. 20 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="http://www.vishay.com/ppg?92334">www.vishay.com/ppg?92334</a>.



# PowerPAK<sup>®</sup> 8 x 8 Case Outline





DIM.	MILLIMETERS				INCHES			
DIN.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
А	0.95	1.00	1.05	0.037	0.039	0.041		
A1	0.00	-	0.05	0.000	-	0.002		
A2		020 ref.			0.008 ref.			
b	0.95	1.00	1.05	0.037	0.039	0.041		
D	7.90	8.00	8.10	0.311	0.315	0.319		
D2	7.10	7.20	7.30	0.280	0.283	0.287		
D3		0.40 BSC			0.016 BSC			
е		2.00 BSC		0.079 BSC				
E	7.90	8.00	8.10	0.311	0.315	0.319		
E2	4.30	4.35	4.40	0.169	0.171	0.173		
E3	0.40 BSC				0.016 BSC			
К	2.75 BSC		0.108 BSC					
L	0.45	0.50	0.55	0.018	0.020	0.022		
N <sup>(3)</sup>		8 8						

#### Notes

 $^{\left( 1\right) }$  Use millimeters as the primary measurement

<sup>(2)</sup> Dimensioning and tolerances conform to ASME Y14.5 M - 1994

<sup>(3)</sup> N is the number of terminals

<sup>(4)</sup> The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body

<sup>(5)</sup> Exact shape and size of this feature is optional

ECN: E20-0518-Rev. B, 28-Sep-2020 DWG: 6041

Revision: 28-Sep-2020



# Recommended Minimum PADs for PowerPAK<sup>®</sup> 8 mm x 8 mm



**Dimensions in millimeters** 

Document Number: 68441



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